



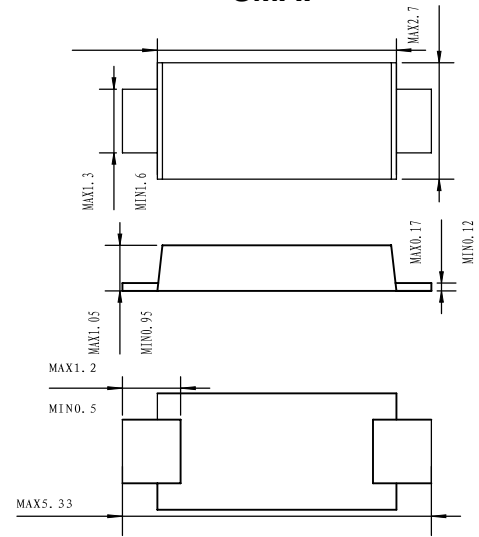
SMAF

FEATURES

- Low profile package
- For surface mounted applications
- Built-in strain relief, ideal for automated placement
- High temperature soldering: 260°C/10 seconds at terminals
- Plastic package has underwriters, laborator flammability classification 94V-0

MECHANICAL DATA

- Case :JEDEC SMAFL, molded plastic over passivated chip
- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity: color band denotes cathode end



Maximum Ratings (@TA = 25°C unless otherwise specified)

Characteristic	Symbol	RS1A AF	RS1B AF	RS1D AF	RS1G AF	RS1J AF	RS1K AF	RS1M AF	UNITS
Marking code		RS1A	RS1B	RS1D	RS1G	RS1J	RS1K	RS1M	UNITS
Maximum recurrent peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current $T_L=90^\circ\text{C}$	$I_{F(AV)}$	1.0							A
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load	I_{FSM}	30							A

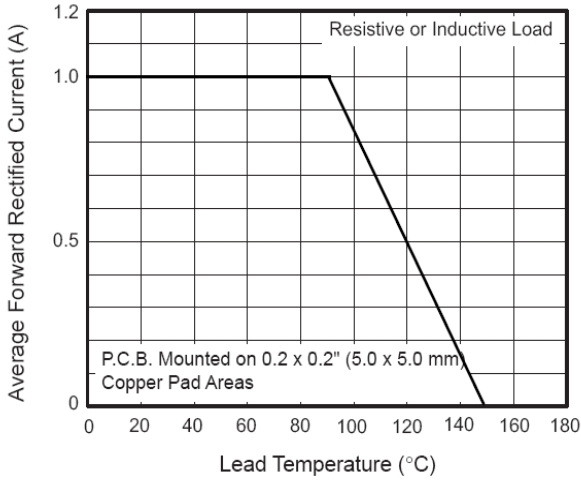
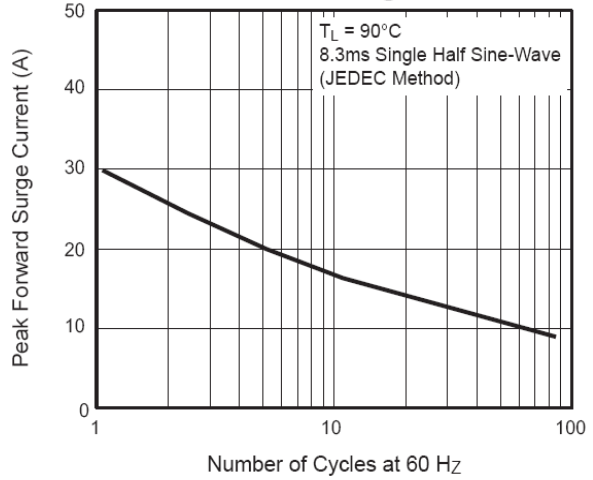
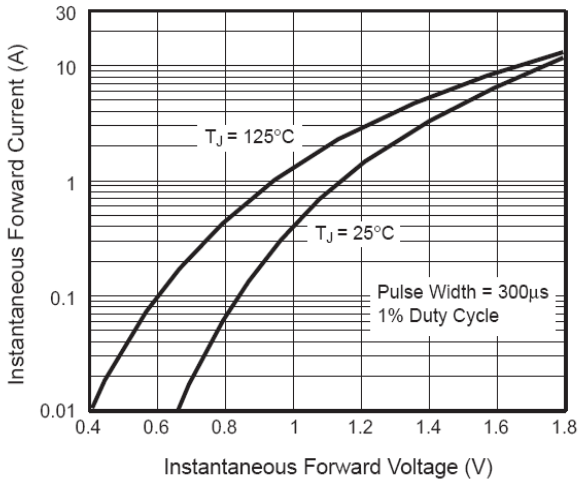
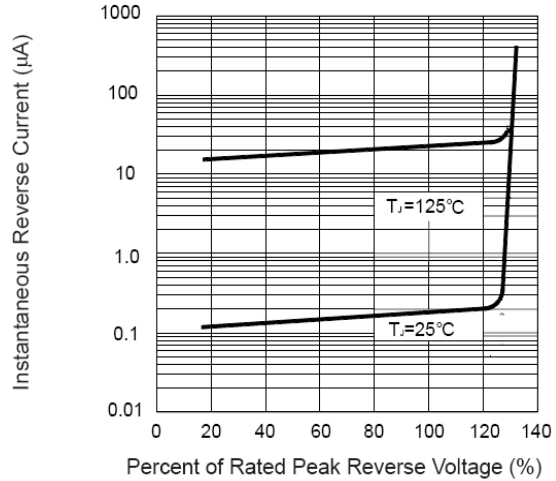
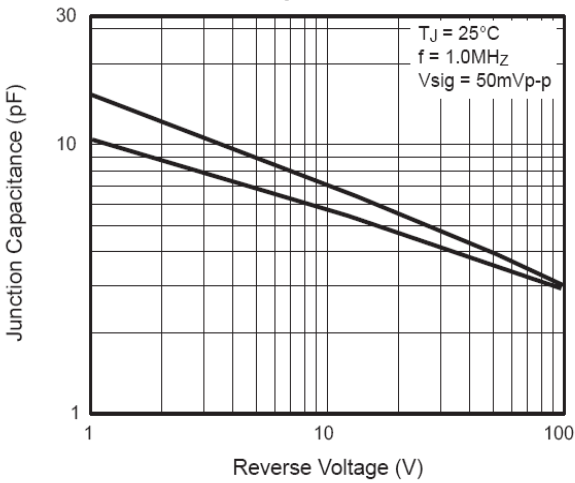
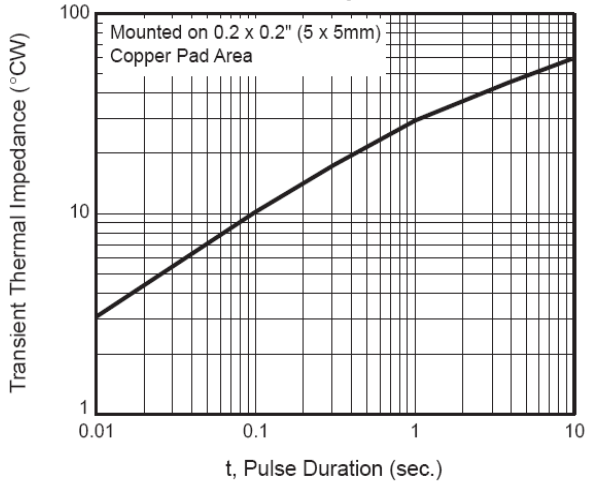
Thermal Characteristics

Characteristic	Symbol	RS1A AF	RS1B AF	RS1D AF	RS1G AF	RS1J AF	RS1K AF	RS1M AF	UNITS	
Typical junction capacitance (Note2)	C_J	10					7.0			p F
Typical thermal resistance (Note3)	$R_{\theta JL}$	17							$^\circ\text{C/W}$	
Operating junction and storage temperature range	$T_J T_{STG}$	- 55 ----- + 150							$^\circ\text{C}$	

Electrical Characteristics (@TA = 25°C unless otherwise specified)

Characteristic	Symbol	RS1A AF	RS1B AF	RS1D AF	RS1G AF	RS1J AF	RS1K AF	RS1M AF	UNITS
Maximum instantaneous forward voltage at 1.0 A	V_F	1.30							V
Maximum reverse current @ $T_A=25^\circ\text{C}$ at rated DC blocking voltage @ $T_A=125^\circ\text{C}$	I_R	5.0				50.0			μA
Typical reverse recovery time (Note1)	t_{rr}	150				250	500		ns

- NOTE: 1.Reverse recovery time test conditions: $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{rr}=0.25\text{A}$
 2. Measured at 1.0MHz and applied reverse voltage of 4.0 Volts
 3. Thermal resistance from junction to lea

Fig. 1 — Forward Current Derating Curve

Fig. 2 — Maximum Non-Repetitive Peak Forward Surge Current

Fig. 3 — Typical Instantaneous Forward Characteristics

Fig. 4 — Typical Reverse Characteristics

Fig. 5 — Typical Junction Capacitance

Fig. 6 — Typical Transient Thermal Impedance


PACKAGE	SPQ/PCS	CARTON SPQ/PCS	CARTON SIZE/CM	CARTON GW/KG	CARTON NW/KG
SMAF	3000/REEL	120000	30.5X30.5X42.5	12.00	11.00
PACKAGE	SPQ/PCS	CARTON SPQ/PCS	CARTON SIZE/CM	CARTON GW/KG	CARTON NW/KG
SMAF	5000/REEL	100000	30.5X30.5X42.5	10.00	9.00